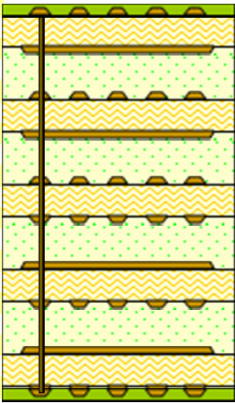


Layer	Cu Thick. (mils)	Cu Foil wt (oz)	DK	Lam. Thick. (mils)	Description
1	2.00	0.5 oz			
2	0.60	0.5 oz	3.48	4.00	Core RO4350B 4.00mils 1080 0.5 oz / 0.5 oz
3	0.60	0.5 oz	3.52	7.40	Prepreg RO4450F 1080(55)/1080(55)
4	0.60	0.5 oz	3.48	4.00	Core RO4350B 4.00mils 1080 0.5 oz / 0.5 oz
5	0.60	0.5 oz	3.52	7.40	Prepreg RO4450F 1080(55)/1080(55)
6	0.60	0.5 oz	3.48	4.00	Core RO4350B 4.00mils 1080 0.5 oz / 0.5 oz
7	0.60	0.5 oz	3.52	7.40	Prepreg RO4450F 1080(55)/1080(55)
8	0.60	0.5 oz	3.48	4.00	Core RO4350B 4.00mils 1080 0.5 oz / 0.5 oz
9	0.60	0.5 oz	3.52	7.40	Prepreg RO4450F 1080(55)/1080(55)
10	2.00	0.5 oz	3.48	4.00	Core RO4350B 4.00mils 1080 0.5 oz / 0.5 oz

Layer	Drill Type	Via Fill	54.40	Thickness over Laminate
1 - 10	PTH	--	58.40	Thickness over Copper
			59.40	Thickness over Soldermask

Impedance Table										
Layer	Structure Type	Coated Microstrip	Target Impedance (ohms)	Impedance Tolerance (ohms)	Target Linewidth (mils)	Differential Spacing * (mils)	Reference Layers	Modelled Linewidth (mils)	Modelled Impedance (ohms)	CoPlaner Space (mils)
1	Single Ended	Yes	50.00	+/-89	5.25	0.00	(2)	5.25	50.41	4.30
1	Single Ended	Yes	50.00	+/-5	7.00	0.00	(2)	7.00	50.09	
1	Edge Coupled Differential	Yes	100.00	+/-10	3.00	5.00	(2)	3.75	100.43	
3	Edge Coupled Differential	---	100.00	+/-10	4.00	4.10	(2, 4)	4.00	99.14	
3	Single Ended	---	50.00	+/-5	5.25	0.00	(2, 4)	5.25	49.98	
5	Single Ended	---	50.00	+/-5	5.50	0.00	(4, 7)	5.50	65.43	
5	Edge Coupled Differential	---	100.00	+/-10	3.00	3.10	(4, 7)	3.00	112.81	
6	Edge Coupled Differential	---	100.00	+/-10	3.00	3.10	(7, 4)	3.00	112.81	
6	Single Ended	---	50.00	+/-5	5.50	0.00	(7, 4)	5.50	65.43	
8	Single Ended	---	50.00	+/-5	5.25	0.00	(9, 7)	5.25	49.98	
8	Edge Coupled Differential	---	100.00	+/-10	4.00	4.10	(9, 7)	4.00	99.14	
10	Edge Coupled Differential	Yes	100.00	+/-10	3.00	5.00	(9)	3.75	100.43	
10	Single Ended	Yes	50.00	+/-89	5.25	0.00	(9)	5.25	50.41	4.30
10	Single Ended	Yes	50.00	+/-5	7.00	0.00	(9)	7.00	50.09	

\* Differential Spacing is measured from the edge line of one differential trace to the edge line of the other.

\* This stack-up was created using estimated copper area percentages. (25% signal, 50% mix, 75% plane) Once data is received minor adjustments of traces and pre-preg thickness may occur.

Process Plating Info  
Final Assembly - 1/10 = Pattern Plate